

General Description

The AGM412MAP combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

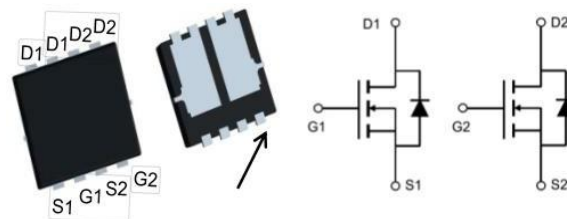
Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
40V	13mΩ	22A

PDFN3*3 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM412M	AGM412MAP	PDFN3*3	----	----	5000

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	40	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) (Note 1)	22	A
	Drain Current-Continuous(Tc=100°C)	15	A
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 2)	80	A
PD	Maximum Power Dissipation(Tc=25°C)	35	w
	Maximum Power Dissipation(Tc=100°C)	7.0	w
EAS	Avalanche energy (Note 3)	15	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹	---	50	°C/W
RθJC	Thermal Resistance Junction-Case ¹	---	3.5	°C/W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	40	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=40V,VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±40V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.0	1.7	2.5	V
gFS	Forward Transconductance	VDS=5V,ID=12A	--	--	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=15A	--	13	15	mΩ
		VGS=4.5V, ID=10A	--	17	22	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=15V,VGS=0V, F=1MHZ	--	475	--	pF
Coss	Output Capacitance		--	75	--	pF
Crss	Reverse Transfer Capacitance		--	45	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	--	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=10V,VDS=15V, ID=10A,RGEN=6.8Ω	--	6.0	--	nS
tr	Turn-on Rise Time		--	12	--	nS
td(off)	Turn-Off Delay Time		--	18	--	nS
tf	Turn-Off Fall Time		--	7	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=15V, ID=10A	--	13	--	nC
Qgs	Gate-Source Charge		--	3.5	--	nC
Qgd	Gate-Drain Charge		--	2.5	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	22	A
VSD	Forward on Voltage	VGS=0V,IS=15A	--	0.86	1.2	V
trr	Reverse Recovery Time	IF=10A , dl/dt=100A/μs , TJ=25℃	--	19	--	ns
Qrr	Reverse Recovery Charge		--	26	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25°C

Typical Characteristics

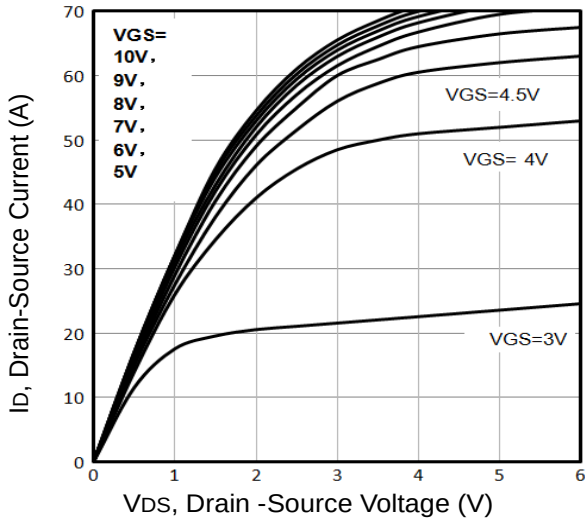


Fig1. Typical Output Characteristics

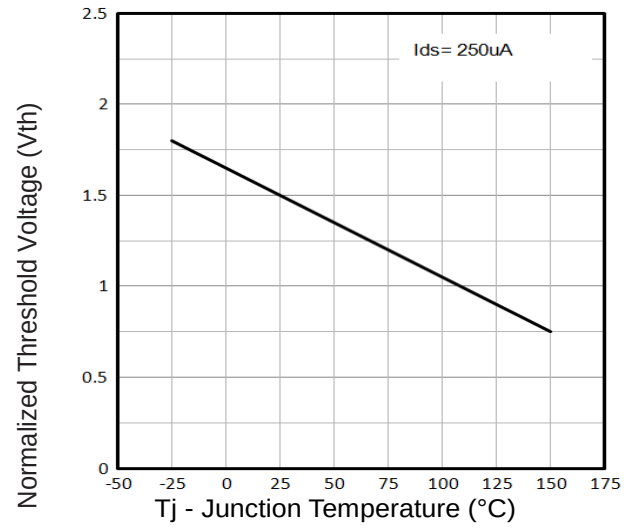


Fig2. Normalized Threshold Voltage Vs. Temperature

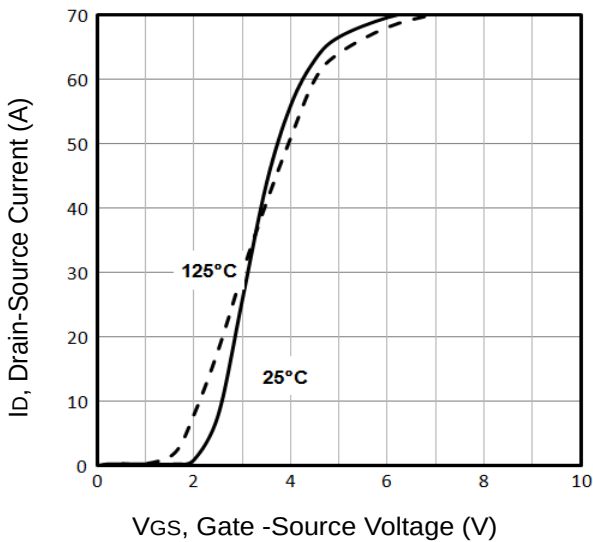


Fig3. Typical Transfer Characteristics

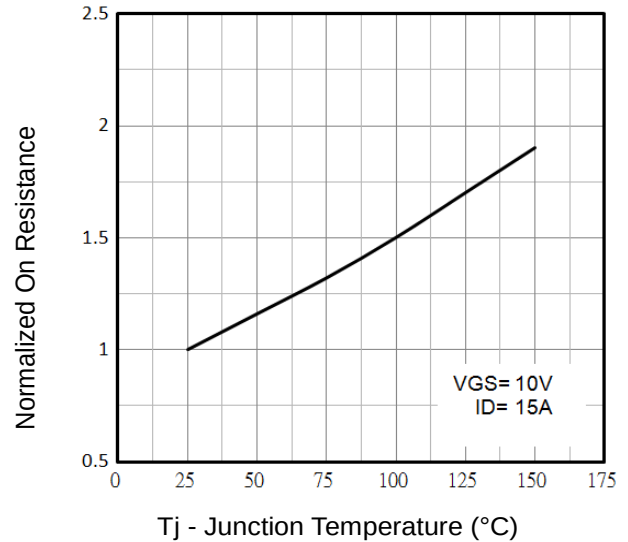


Fig4. Normalized On-Resistance Vs. Temperature

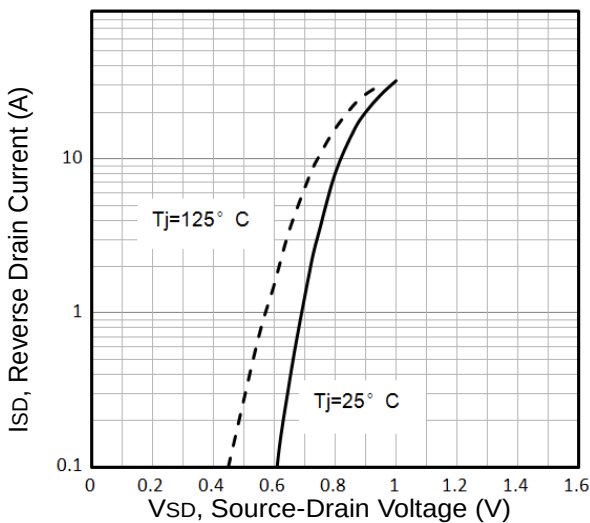


Fig5. Typical Source-Drain Diode Forward Voltage

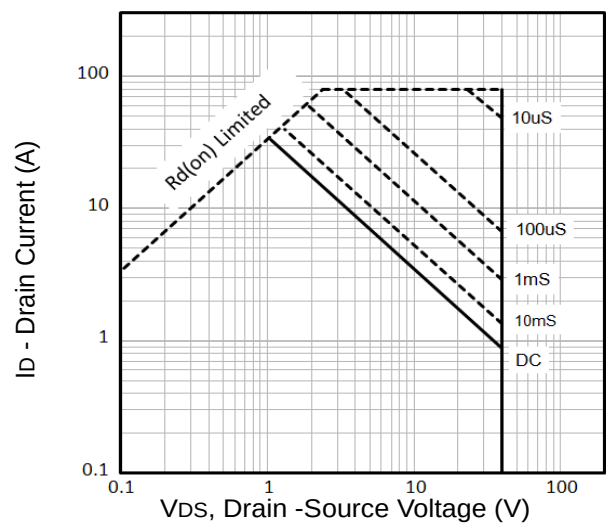
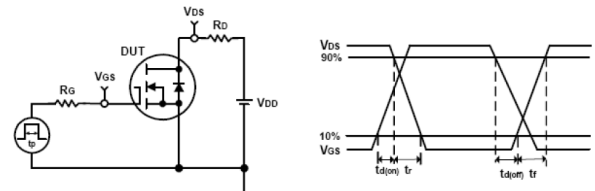
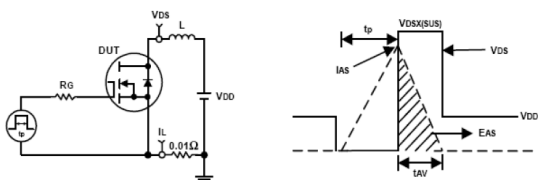
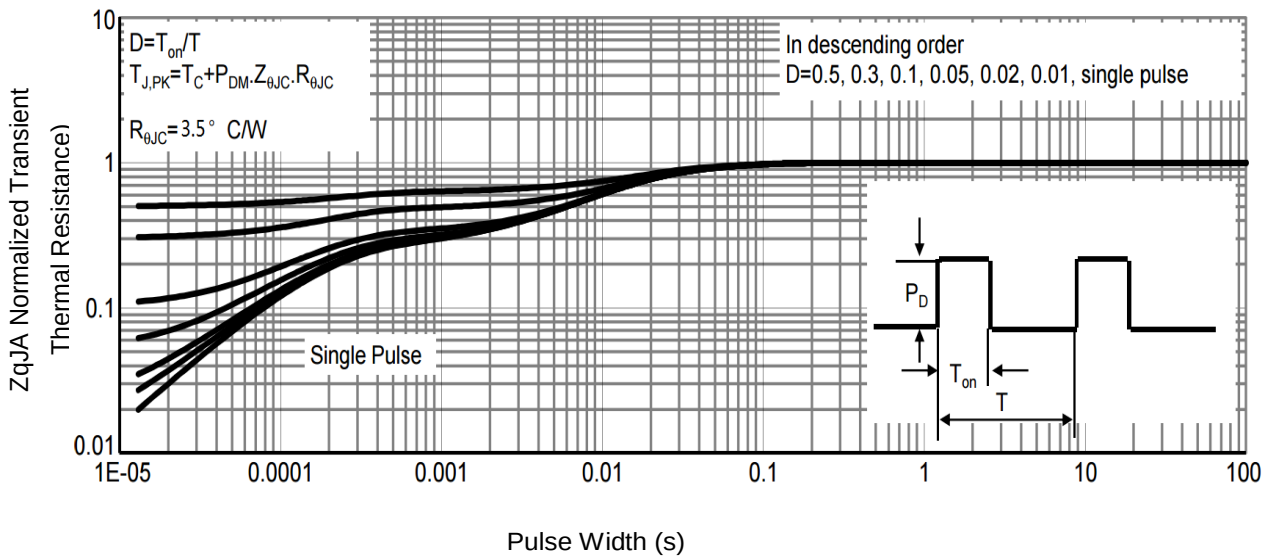
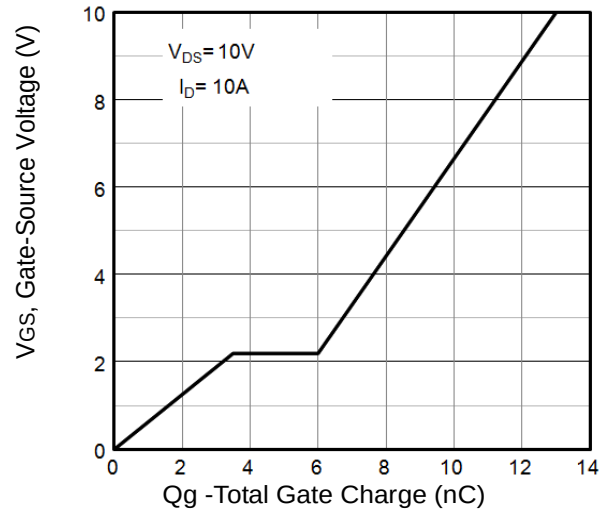
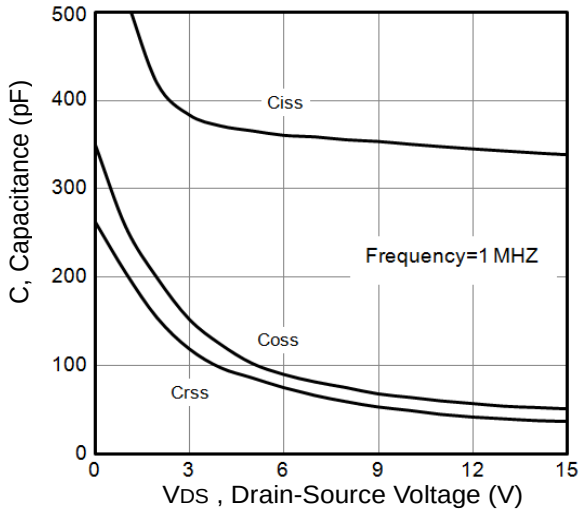
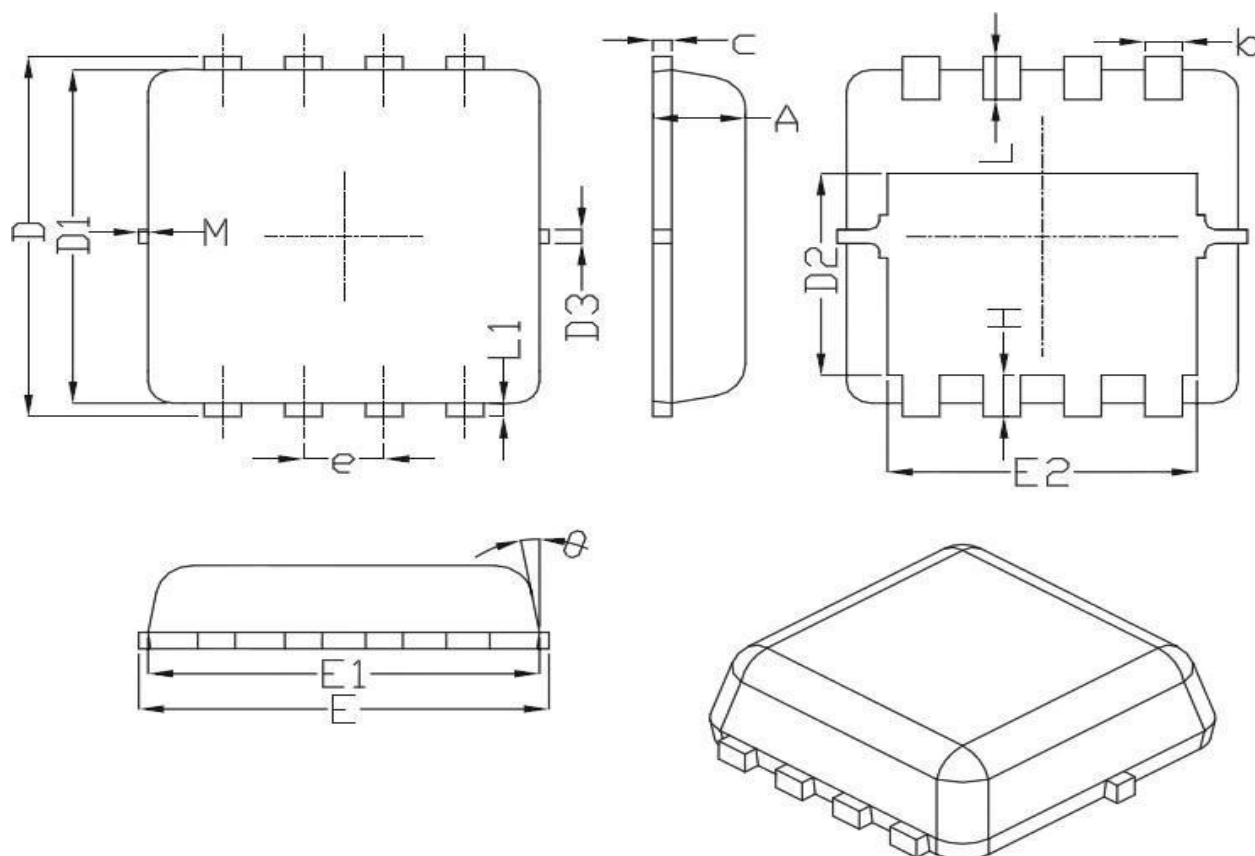


Fig6. Maximum Safe Operating Area

Typical Characteristics



PDFN3333 Package Outline Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.75	0.80	b	0.25	0.30	0.35
C	0.10	0.15	0.25	D	3.25	3.35	3.45
D1	3.00	3.10	3.20	D2	1.78	1.88	1.98
D3	--	0.13	--	E	3.20	3.30	3.40
E1	3.00	3.15	3.20	E2	2.39	2.49	2.59
e	0.65BSC			H	0.30	0.39	0.50
L	0.30	0.40	0.50	L1	--	0.13	--
θ	--	10°	12°	M	*	*	0.15
*Not specified							

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